L Number	Hits	Search Text	DB	Time stamp
3	1697	34/164,165,166,279,288,340,342,397,423,425,444,505,593,595.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/07 09:00
4	4	34/164,165,166,279,288,340,342,397,423,425,444,505,593,595.ccls. and (chamber with (rotary or rotat$3) with drain$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/07 09:04
5	96	34/164,165,166,279,288,340,342,397,423,425,444,505,593,595.ccls. and (chamber with (rotary or rotat$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/07 09:05
6	49	34/164,165,166,279,288,340,342,397,423,425,444,505,593,595.ccls. and ((vessel or tank or container or chamber) near2 (rotary or rotat$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/07 09:06
7	149	34/164,165,166,279,288,340,342,397,423,425,444,505,593,595.ccls. and ((vessel or tank or container or chamber) with (rotary or rotat$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/07 09:05
8	6596	134/2,10,21,25.4,30,32,34.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/07 09:06
9	8266	134/2,10,21,25.4,30,32,34.ccls. or 34/164,165,166,279,288,340,342,397,423,425,444,505,593,595.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/07 09:06
10	223	(134/2,10,21,25.4,30,32,34.ccls. or 34/164,165,166,279,288,340,342,397,423,425,444,505,593,595.ccls. and ((vessel or tank or container or chamber) near2 (rotary or rotat$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/07 09:06
11	94	((134/2,10,21,25.4,30,32,34.ccls. or 34/164,165,166,279,288,340,342,397,423,425,444,505,593,595.ccls. and ((vessel or tank or container or chamber) near2 (rotary or rotat$3))) and drain$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/07 09:07
-	36869	134/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/03 10:45
-	123	134/$.ccls. and (chamber with (rotary or rotat$3) with drain$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/07 09:01
-	18	134/$.ccls. and (chamber near2 (rotary or rotat$3) with drain$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/03 10:46
-	6593	134/2,10,21,25.4,30,32,34.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/07 09:06

-	174	134/2,10,21,25.4,30,32,34.ccls. and ((rotary or rotat$3) near2 (chamber or vessel or container or tank))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/03 16:15
-	85	(134/2,10,21,25.4,30,32,34.ccls. and ((rotary or rotat$3) near2 (chamber or vessel or container or tank))) and drain$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/03 16:04
-	2988	(eric near2 bergman).in. or (dana near2 scranton).in. or lund.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/03 16:06
-	116	(eric near2 bergman).in. or (dana near2 scranton).in. or ((gil or worm or eric) near2 lund).in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/03 16:06
-	7	((eric near2 bergman).in. or (dana near2 scranton).in. or ((gil or worm or eric) near2 lund).in.) and (chamber with (rotary or rotat$3) with drain$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/03 16:07
-	6225	134/2,10,21,25.4,30,32-33.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/03 16:07
-	5379	134/2,21,25.4,30,32-33.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/03 16:15
-	164	134/2,21,25.4,30,32-33.ccls. and ((rotary or rotat$3) near2 (chamber or vessel or container or tank))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/03 16:08
-	7300	134/2,21,25.4,30,32-33,117,119,120,121,902.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/03 16:19
-	262	134/2,21,25.4,30,32-33,117,119,120,121,902.ccls. and ((rotary or rotat$3) near2 (chamber or vessel or container or tank))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/03 16:16
-	190	(134/2,21,25.4,30,32-33,117,119,120,121,902.ccls. and ((rotary or rotat$3) near2 (chamber or vessel or container or tank))) and (semiconductor or wafer or substrate or workpiece)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/03 16:16
-	5	134/117,119,120,121.ccls. and 134/902.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/03 16:22
-	102	134/120.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/03 16:20

-	6	134/120.ccls. and drain	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/03 16:20
-	11	134/120.ccls. and drain$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/03 16:20
-	19	134/117,119,120,121.ccls. and (semiconductor or wafer or substrate or workpiece)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/03 16:22